



US 20240222969A1

(19) **United States**

(12) **Patent Application Publication**
MATSUMOTO

(10) **Pub. No.: US 2024/0222969 A1**

(43) **Pub. Date: Jul. 4, 2024**

(54) **POWER SUPPLY SYSTEM FOR
SEMICONDUCTOR MANUFACTURING
SYSTEM GROUP**

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(21) Appl. No.: **18/605,837**

(22) Filed: **Mar. 15, 2024**

Related U.S. Application Data

(63) Continuation of application No. PCT/JP2023/
002579, filed on Jan. 27, 2023.

(30) **Foreign Application Priority Data**

Feb. 10, 2022 (JP) 2022-019863

Publication Classification

(51) **Int. Cl.**
H02J 3/00 (2006.01)

H01L 21/67 (2006.01)

(52) **U.S. Cl.**

CPC **H02J 3/00** (2013.01); **H01L 21/67167**
(2013.01); **H01L 21/67173** (2013.01); **H01L**
21/67178 (2013.01)

(57)

ABSTRACT

A power supply system includes a power supply, a plurality of power feeding devices coupled to the power supply, a plurality of semiconductor manufacturing systems, and processing circuitry. Each of the plurality of semiconductor manufacturing systems includes a plurality of substrate processing chambers and a power receiving device that wirelessly receives power from a power feeding device of the plurality of power feeding devices. The processing circuitry controls the power distribution unit to adjust a maximum effective power supplied from the power supply to each of the plurality of semiconductor manufacturing systems through the power feeding device based on a power use status in each of the plurality of semiconductor manufacturing systems.

